

Title (en)

Process for producing semiconductor device substrate.

Title (de)

Verfahren zur Herstellung eines Substrats für Halbleiteranordnungen.

Title (fr)

Procédé de fabrication d'un substrat pour dispositif semi-conducteur.

Publication

EP 0413547 A2 19910220 (EN)

Application

EP 90308908 A 19900814

Priority

JP 21176189 A 19890817

Abstract (en)

A process of producing an SOI-structured semiconductor device substrate, comprising bonding polished surfaces of two Si-monocrystal wafers (1a, 1b), at least one of which surfaces bears an oxide film (1c), and uniformly eliminating part of the thickness of one of the wafers (1b) parallel to the polished surface, characterised by: reducing the diameter of said one wafer (1b) so that it is slightly smaller than that of the other wafer (1a), thereby exposing an unbonded uniform annular periphery on the surface of said other wafer (1a); forming, on the surface of said one wafer (1b) and said periphery, a material (1d) providing greater resistance to polishing than said one wafer (1b); and polishing said one wafer (1b). Even when only a few μ m thick, the material, e.g. SiO₂, provides accurate thickness control of the thin film, and thus acts as a polishing guard.

IPC 1-7

H01L 21/302; **H01L 21/76**

IPC 8 full level

H01L 21/304 (2006.01); **H01L 21/02** (2006.01); **H01L 21/20** (2006.01); **H01L 21/306** (2006.01); **H01L 21/762** (2006.01); **H01L 27/12** (2006.01)

CPC (source: EP US)

H01L 21/2007 (2013.01 - EP US); **H01L 21/30625** (2013.01 - EP US); **H01L 21/76251** (2013.01 - EP US); **Y10S 148/012** (2013.01 - EP US); **Y10S 148/135** (2013.01 - EP US)

Cited by

EP0561532A3; EP0451993A3; EP0547684A3; EP0570321A3; WO9415356A1; EP2602810B1; EP0444942B1

Designated contracting state (EPC)

DE FR GB

DOCDB simple family (publication)

EP 0413547 A2 19910220; **EP 0413547 A3 19910320**; **EP 0413547 B1 19930421**; DE 69001411 D1 19930527; DE 69001411 T2 19931118; JP H0376118 A 19910402; JP H0636414 B2 19940511; US 5032544 A 19910716

DOCDB simple family (application)

EP 90308908 A 19900814; DE 69001411 T 19900814; JP 21176189 A 19890817; US 56597390 A 19900813